

09/872,713

1-10. (CANCELED).

11. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the thermal conductive material is plasticized at 60°C under a pressure equal to or above 6.0 g/cm².

12. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the unvulcanized organic material has a melting transition in the range of 30-70°C and a viscosity at 100°C is equal to or above 70,000cP, a weight ratio of the filler to the thermal conductive material is in the range of 30-90%.

13. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the thermal conductive material is in an elastomeric state at room temperature.

14. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the organic material is an olefin resin.

15. (CANCELED)

16. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the filler is at least one of ceramics, metallic powder, metallic magnetic body and carbon fiber.

17. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the filler is a material serving as an electromagnetic shield.

18. (CANCELED)

19. (CURRENTLY AMENDED) A thermal conductive material comprising:
an unvulcanized EPDM material ~~having a weight average molecular weight of between 7,000-50,000~~; and
a filler having a higher thermal conductivity than the unvulcanized EPDM material,

wherein the thermal conductive material is plasticized at a temperature in the range of 30-65°C and the thermal conductive material changes form to flexibly correspond to a form of a surface of a member with which the thermal conductive material comes in contact.